

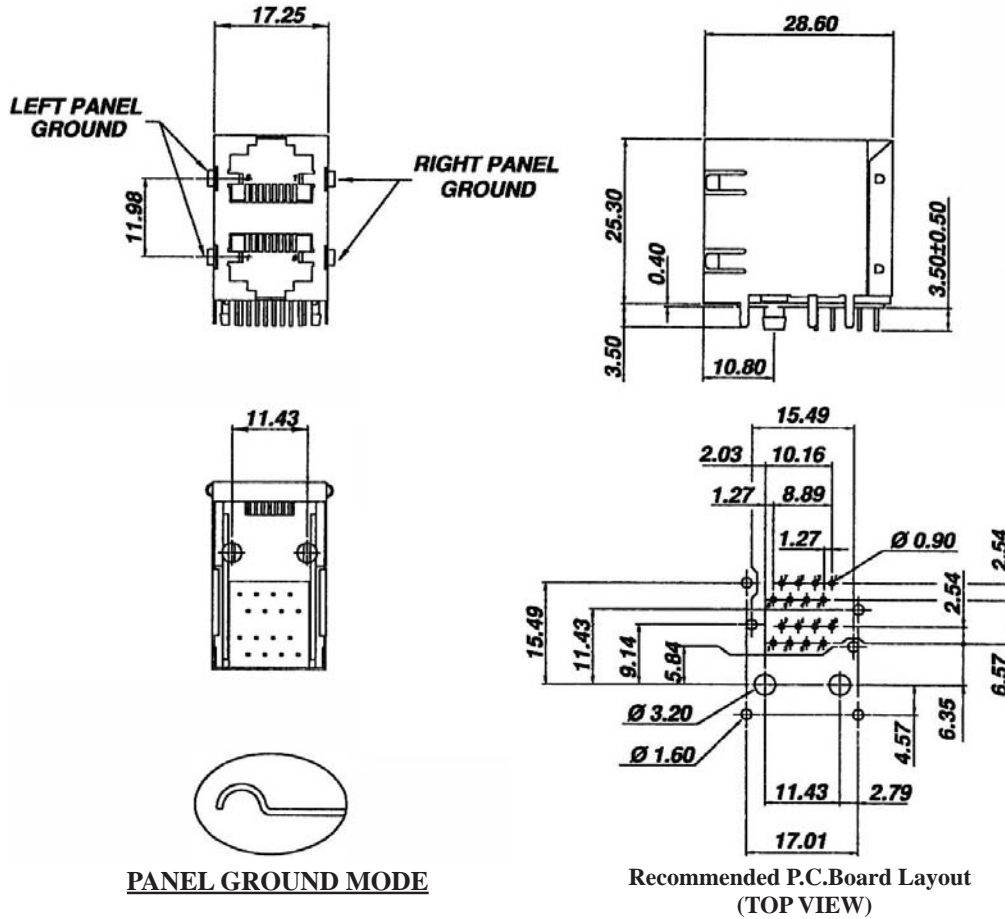
# SIDE ENTRY 2-PORT DOUBLE LEVEL MODULAR PCB JACK WITH INNER SHIELD 8P PROFILE=25.30MM (FULLY SHIELDED)

## SPECIFICATIONS

**Insulation Resistance:** 500MΩ Min.  
**Contact Resistance:** 20mΩ Max.  
**Rating Current:** 1.5A Max.  
**Rating Voltage:** 120V AC.  
**Dielectric Voltage:** 1000 Vrms 60 Sec. Min.  
**Temperature Range:** -40°C / +85°C  
**Durability:** 500 Mating cycles Min.

## MATERIALS

**Housing:** PBT Glass Filled (UL 94V-0)  
**Soldering Temperature:** 235°C  
**Color:** Black  
**Spring Wire:** Phosphor Bronze  
                     Gold plating Over Nickel  
**Shield:** Brass plating Nickel Alloy  
**All materials must be RoHS compliant.**



Recommended P.C.Board Layout (TOP VIEW)

## ORDERING INFORMATION:

P/N MJDE - 88 x B 02  
                  1 2 3

1. NO. OF POSITIONS & CONTACTS:  
"88" 8P8C
2. CONTACT FINISH:  
"A" 6 MICROINCH GOLD  
"B" 15 MICROINCH GOLD  
"C" 30 MICROINCH GOLD  
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:  
02

NOTE: P/N MJDEHT-88xB02 for High Temp. Version

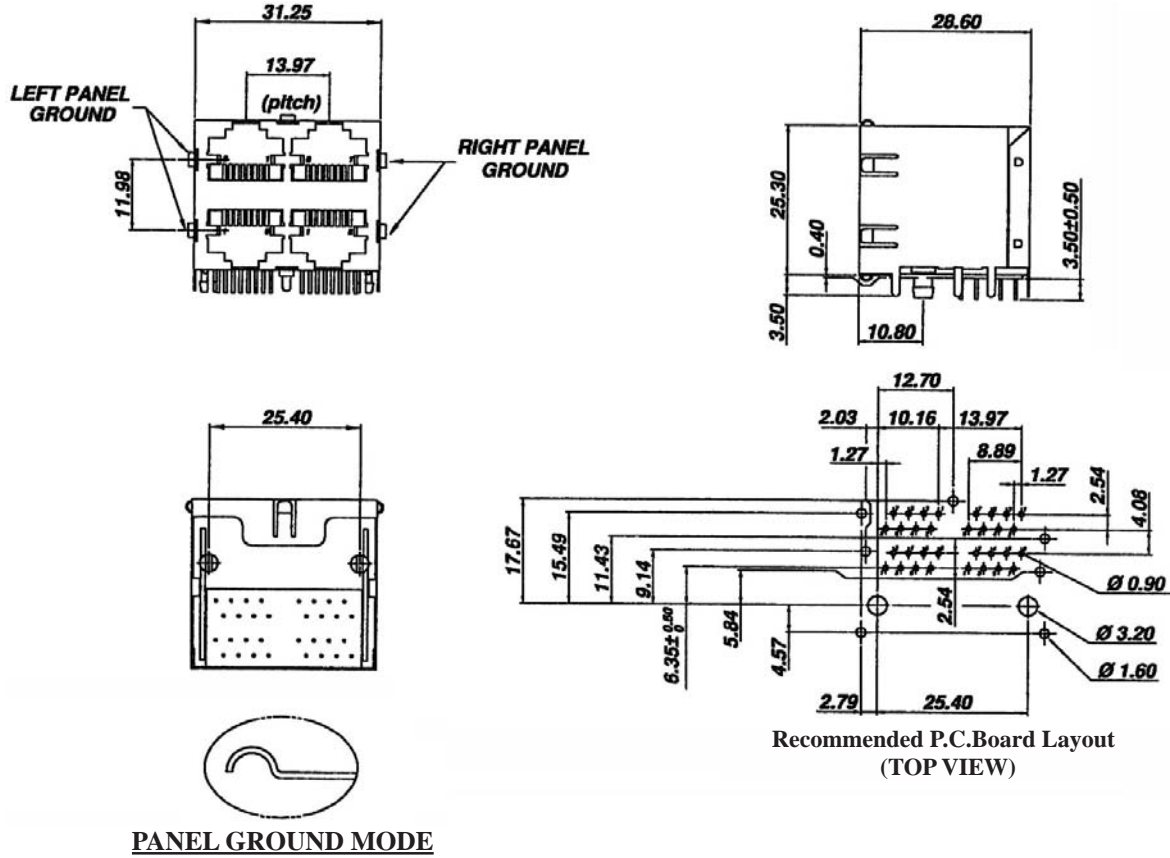
# SIDE ENTRY 4-PORT DOUBLE LEVEL MODULAR PCB JACK WITH INNER SHIELD 8P PROFILE=25.30MM (FULLY SHIELDED)

## SPECIFICATIONS

**Insulation Resistance:** 500MΩ Min.  
**Contact Resistance:** 20mΩ Max.  
**Rating Current:** 1.5A Max.  
**Rating Voltage:** 120V AC.  
**Dielectric Voltage:** 1000 Vrms 60 Sec. Min.  
**Temperature Range:** -40°C / +85°C  
**Durability:** 500 Mating cycles Min.

## MATERIALS

**Housing:** PBT Glass Filled (UL 94V-0)  
**Soldering Temperature:** 235°C  
**Color:** Black  
**Spring Wire:** Phosphor Bronze  
                     Gold plating Over Nickel  
**Shield:** Brass plating Nickel Alloy  
**All materials must be RoHS compliant.**



## ORDERING INFORMATION:

P/N MJDE - 88 x B 04  
 $\frac{1}{2} \frac{3}{3}$

1. NO. OF POSITIONS & CONTACTS:  
"88" 8P8C
2. CONTACT FINISH:  
"A" 6 MICROINCH GOLD  
"B" 15 MICROINCH GOLD  
"C" 30 MICROINCH GOLD  
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:  
04

NOTE: P/N MJDEHT-88xB04 for High Temp. Version

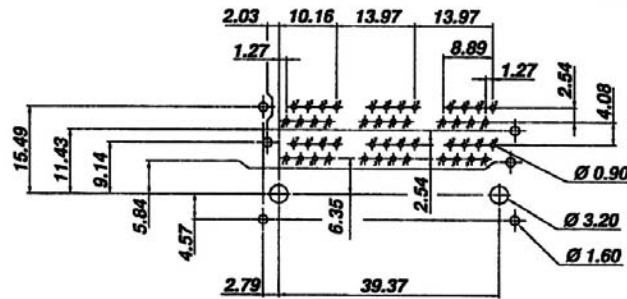
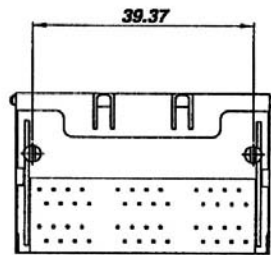
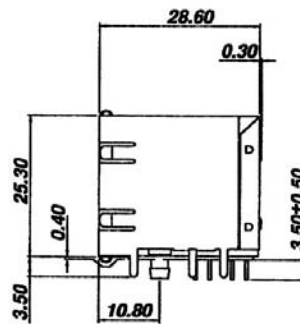
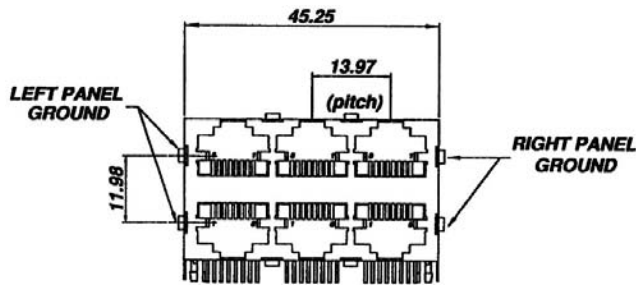
## SIDE ENTRY 6-PORT DOUBLE LEVEL MODULAR PCB JACK WITH INNER SHIELD 8P PROFILE=25.30MM (FULLY SHIELDED)

### SPECIFICATIONS

**Insulation Resistance:** 500MΩ Min.  
**Contact Resistance:** 20mΩ Max.  
**Rating Current:** 1.5A Max.  
**Rating Voltage:** 120V AC.  
**Dielectric Voltage:** 1000 Vrms 60 Sec. Min.  
**Temperature Range:** -40°C / +85°C  
**Durability:** 500 Mating cycles Min.

### MATERIALS

**Housing:** PBT Glass Filled (UL 94V-0)  
**Soldering Temperature:** 235°C  
**Color:** Black  
**Spring Wire:** Phosphor Bronze  
                     Gold plating Over Nickel  
**Shield:** Brass plating Nickel Alloy  
**All materials must be RoHS compliant.**



Recommended P.C. Board Layout (TOP VIEW)



PANEL GROUND MODE

### ORDERING INFORMATION:

P/N MJDE - 88 x B 06  
                   1 2 3

1. NO. OF POSITIONS & CONTACTS:  
"88" 8P8C
2. CONTACT FINISH:  
"A" 6 MICROINCH GOLD  
"B" 15 MICROINCH GOLD  
"C" 30 MICROINCH GOLD  
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:  
06

NOTE: P/N MJDEHT-88xB06 for High Temp. Version

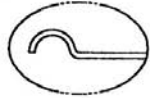
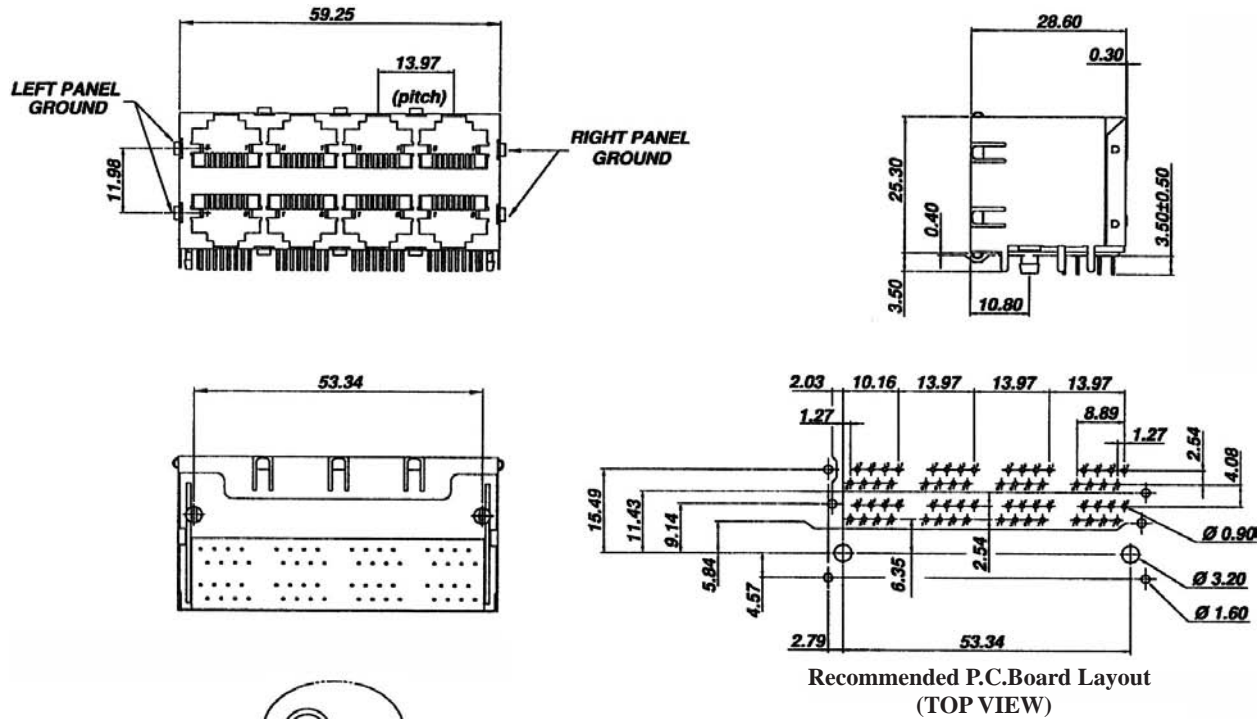
# SIDE ENTRY 8-PORT DOUBLE LEVEL MODULAR PCB JACK WITH INNER SHIELD 8P PROFILE=25.30MM (FULLY SHIELDED)

## SPECIFICATIONS

**Insulation Resistance:** 500MΩ Min.  
**Contact Resistance:** 20mΩ Max.  
**Rating Current:** 1.5A Max.  
**Rating Voltage:** 120V AC.  
**Dielectric Voltage:** 1000 Vrms 60 Sec. Min.  
**Temperature Range:** -40°C / +85°C  
**Durability:** 500 Mating cycles Min.

## MATERIALS

**Housing:** PBT Glass Filled (UL 94V-0)  
**Soldering Temperature:** 235°C  
**Color:** Black  
**Spring Wire:** Phosphor Bronze  
                     Gold plating Over Nickel  
**Shield:** Brass plating Nickel Alloy  
**All materials must be RoHS compliant.**



**PANEL GROUND MODE**

## ORDERING INFORMATION:

**P/N MJDE - 88 x B 08**  
 $\frac{1}{2} \frac{3}{3}$

1. NO. OF POSITIONS & CONTACTS:  
"88" 8P8C
2. CONTACT FINISH:  
"A" 6 MICROINCH GOLD  
"B" 15 MICROINCH GOLD  
"C" 30 MICROINCH GOLD  
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:  
08

NOTE: P/N MJDEHT-88xB08 for High Temp. Version

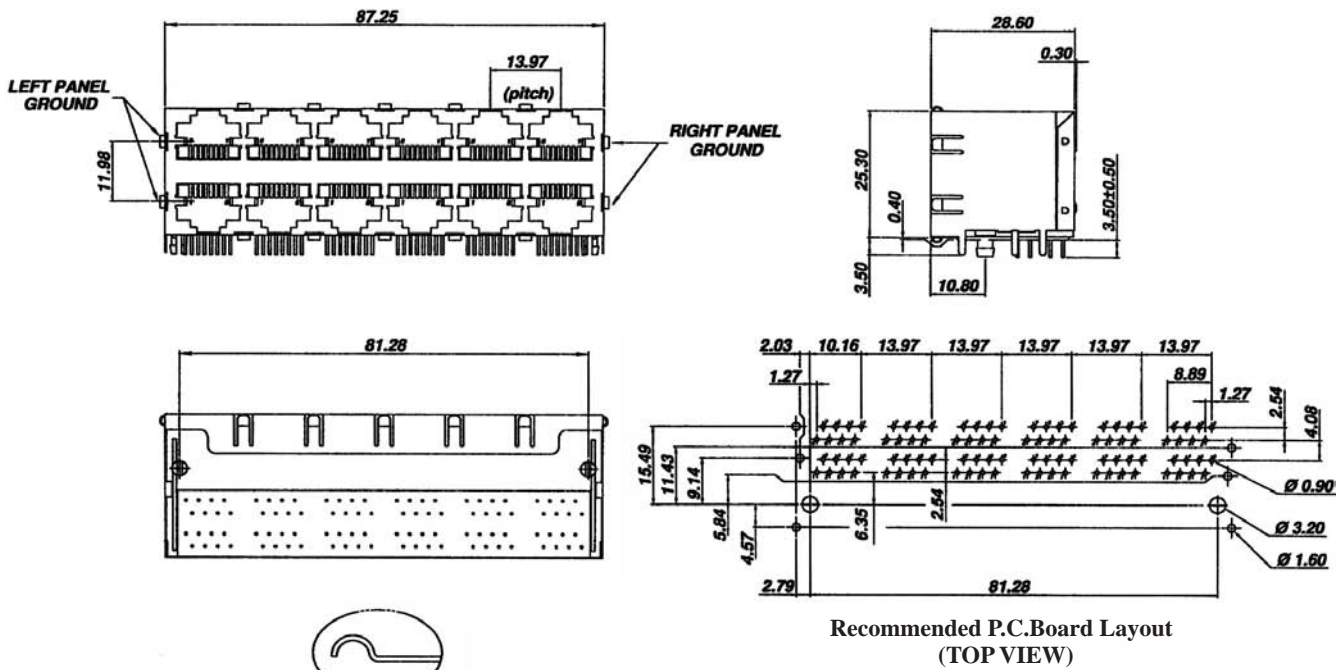
## SIDE ENTRY 12-PORT DOUBLE LEVEL MODULAR PCB JACK WITH INNER SHIELD 8P PROFILE=25.30MM (FULLY SHIELDED)

### SPECIFICATIONS

Insulation Resistance: 500MΩ Min.  
 Contact Resistance: 20mΩ Max.  
 Rating Current: 1.5A Max.  
 Rating Voltage: 120V AC.  
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.  
 Temperature Range: -40°C / +85°C  
 Durability: 500 Mating cycles Min.

### MATERIALS

Housing: PBT Glass Filled (UL 94V-0)  
 Soldering Temperature: 235°C  
 Color: Black  
 Spring Wire: Phosphor Bronze  
 Gold plating Over Nickel  
 Shield: Brass plating Nickel Alloy  
 All materials must be RoHS compliant.



PANEL GROUND MODE

### ORDERING INFORMATION:

P/N MJDE - 88 x B  $\frac{1}{2}$   $\frac{1}{3}$

- NO. OF POSITIONS & CONTACTS:  
"88" 8P8C
- CONTACT FINISH:  
"A" 6 MICROINCH GOLD  
"B" 15 MICROINCH GOLD  
"C" 30 MICROINCH GOLD  
"D" 50 MICROINCH GOLD
- NO. OF PORTS:  
12

NOTE: P/N MJDEHT-88xB12 for High Temp. Version

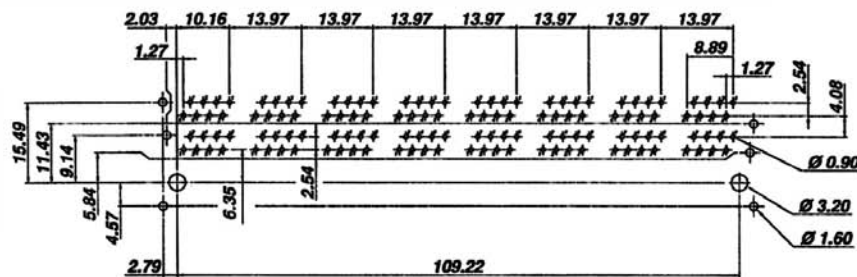
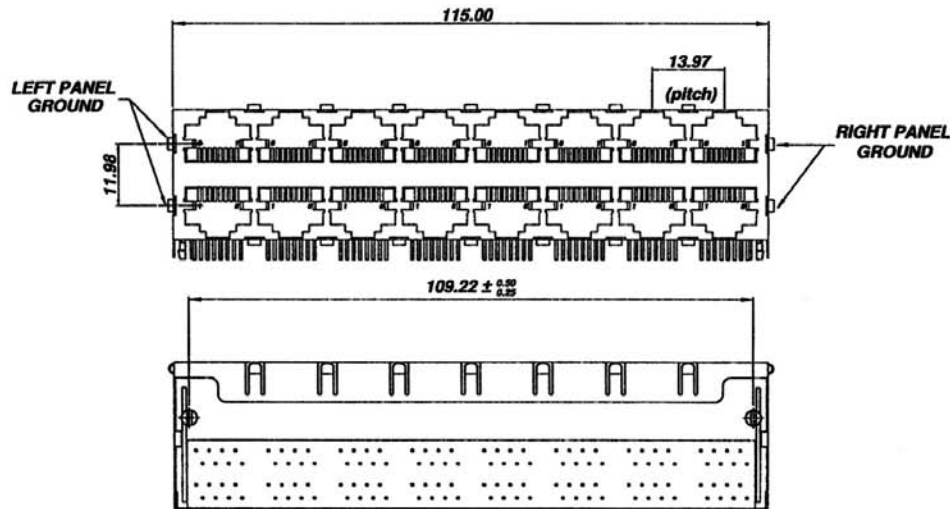
## SIDE ENTRY 16-PORT DOUBLE LEVEL MODULAR PCB JACK WITH INNER SHIELD 8P PROFILE=25.30MM (FULLY SHIELDED)

### SPECIFICATIONS

Insulation Resistance: 500MΩ Min.  
 Contact Resistance: 20mΩ Max.  
 Rating Current: 1.5A Max.  
 Rating Voltage: 120V AC.  
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.  
 Temperature Range: -40°C / +85°C  
 Durability: 500 Mating cycles Min.

### MATERIALS

Housing: PBT Glass Filled (UL 94V-0)  
 Soldering Temperature: 235°C  
 Color: Black  
 Spring Wire: Phosphor Bronze  
 Gold plating Over Nickel  
 Shield: Brass plating Nickel Alloy  
 All materials must be RoHS compliant.



Recommended P.C. Board Layout  
(TOP VIEW)

### ORDERING INFORMATION:

P/N MJDE - 88 x B 16  
 1 2 3

1. NO. OF POSITIONS & CONTACTS:  
"88" 8P8C
2. CONTACT FINISH:  
"A" 6 MICROINCH GOLD  
"B" 15 MICROINCH GOLD  
"C" 30 MICROINCH GOLD  
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:  
16

NOTE: P/N MJDEHT-88xB16 for High Temp. Version